IN THE CLAIMS

Please cancel claims 1-109 and add the following new claims:

110 [(new)] A method for plating a film to a desired thickness on a surface of a substrate, comprising:

providing a plurality of stacked plating modules and a substrate transferring mechanism;

picking up a substrate from a substrate holder with the substrate transferring mechanism;

loading the substrate into a first one of the stacked plating modules with the substrate transferring mechanism;

plating a film on the substrate in the first one of the stacked plating modules; and

returning the substrate to said substrate holder with the substrate transferring mechanism.

111 [(new)] The method of claim 110, further comprising:

after plating the film on the substrate, drying the substrate by at least one of spinning the substrate or directing drying gas onto the substrate.

112 [(new)] The method of claim 110, wherein at least a second one of the plurality of plating modules is a cleaning module, the method further comprising:

after plating the film on the substrate, picking up the substrate with the substrate transferring mechanism from the first one of the stacked plating modules;

placing the substrate into the second one of the stacked plating modules for cleaning;

cleaning the substrate in the second one of the stacked plating modules; and

drying the substrate in the second one of the stacked plating modules.

113 [(new)] An automated tool for plating a film on a substrate, comprising:

at least two plating baths positioned in a stacked relationship;

at least one substrate holder;

a substrate transferring mechanism;

a frame supporting said plating baths, said substrate holder and said substrate transferring mechanism; and

a control system in communication with said substrate transferring mechanism, substrate holder and said plating baths configured to continuously perform uniform film deposition on the substrate.

114. [(new)] The automated tool of claim 113, further comprising:

at least two cleaning modules positioned in a stacked relationship with said at least two plating baths.

115. [(new)] The automated tool of claim 113, wherein the substrate transferring mechanism includes a telescoping member movable with three degrees of freedom.

116. [(new)] The automated tool of claim 113, wherein said substrate transferring mechanism is mounted on a bottom portion of said frame.

117. [(new)] The automated tool of claim 113, wherein said substrate transferring mechanism is mounted on a top portion of said frame.

118. [(new)] The automated tool of claim 113, further comprising at least a second set of plating baths positioned in a stacked relationship and at least two additional cleaning modules positioned in a stacked relationship with said second set of plating baths.

REMARKS

The present application is a divisional of U.S. Patent Application Serial No. 09/232,864, filed January 15, 1999, which claims the benefit of U.S. Provisional Application Serial No. 60/094,215, filed July 27, 1998, and U.S. Provisional Application Serial No. 60/074,466, filed February 12, 1998.